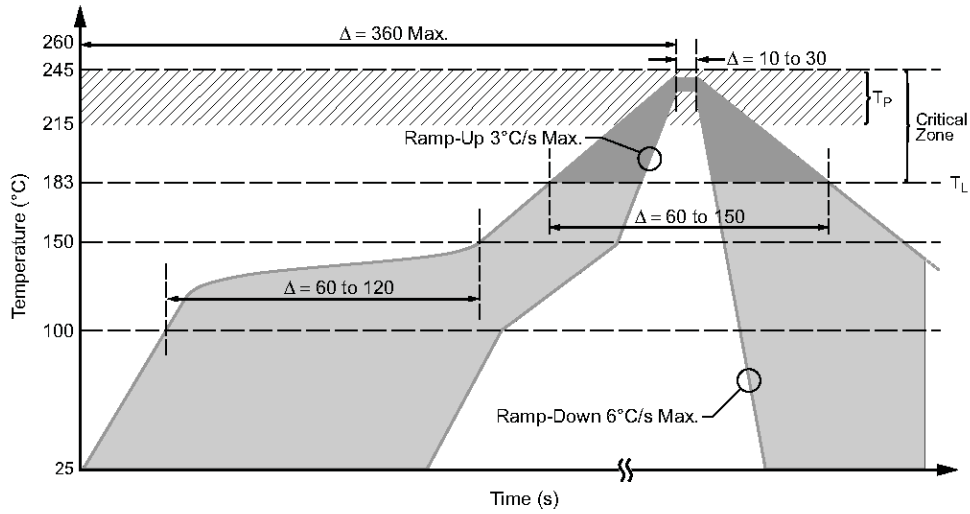
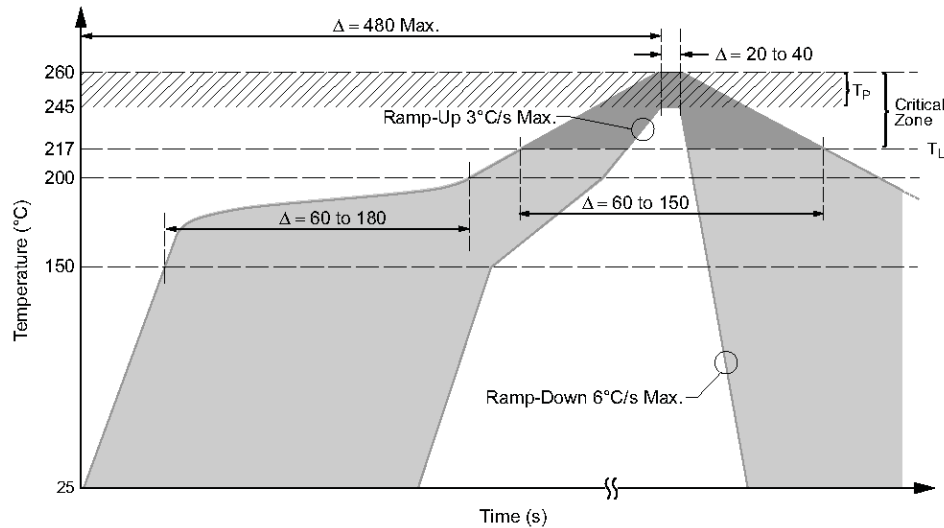


## Soldering Methods for Xmultiple Terminal Blocks

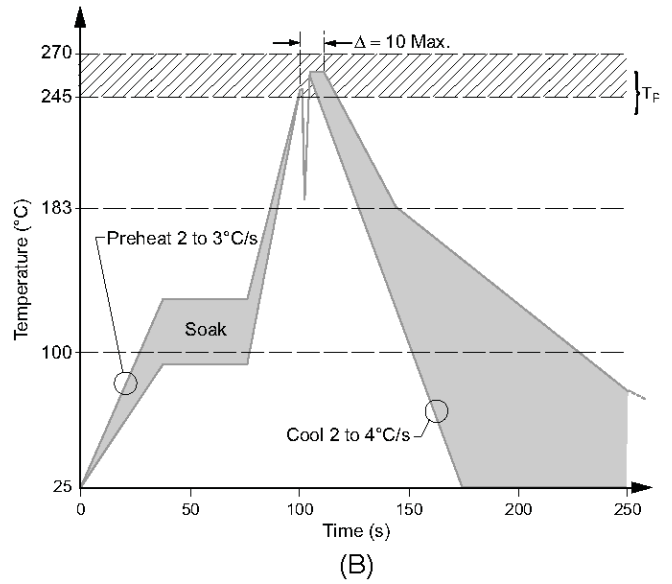
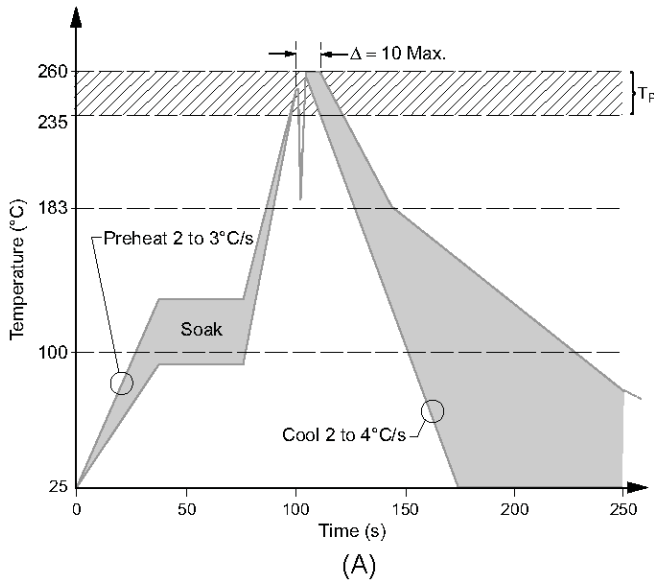


Solder Reflow Profile for SMD Using Traditional Tin-Lead Solder. The typical acceptable maximum temperature range,  $T_P$ , is 215°C to 245°C. Temperatures refer to upper surface of the package case.



Solder Reflow Profile for SMD Using Lead (Pb) Free Solder. The typical acceptable maximum temperature range,  $T_P$ , is 245°C to 260°C. Temperatures refer to upper surface of the package case.

## Soldering Methods for Xmultiple Terminal Blocks



Solder Reflow Profile for Through-Hole Wave Solder Using (A) Traditional Tin-Lead Solder and (B) Pb-free solder.